



DZ26043×0L

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Silicon epitaxial planar type

For constant voltage / For surge absorption circuit  
DZ27043 in ML2 type package

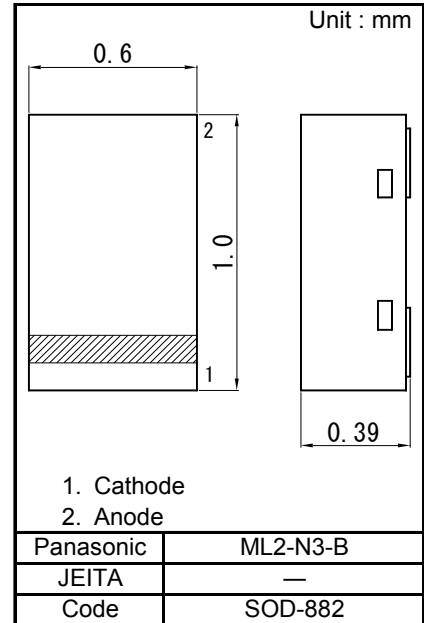
■ Features

- Excellent rising characteristics of zener current IZ
- Low zener operating resistance RZ
- Halogen-free / RoHS compliant  
(EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)

■ Marking Symbol :9J or 9U

■ Packaging

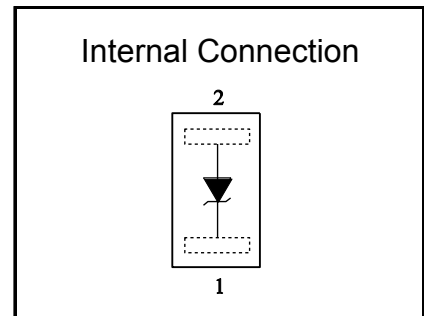
Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation *1	PT	100	mW
Electrostatic discharge *2	ESD	±15	kV
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

Note) \*1 PT = 100 mW achieved with a printed circuit board.  
\*2 Test method:IEC61000\_4\_2  
( C = 150 pF , R = 330 Ω , Contact discharge : 10 times )



■ Electrical Characteristics Ta = 25 °C ± 3 °C

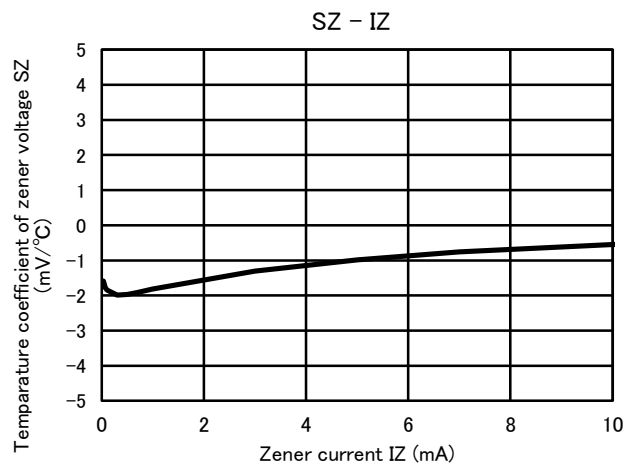
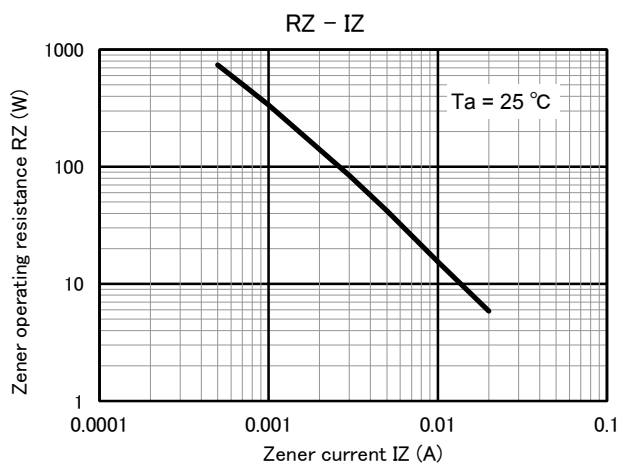
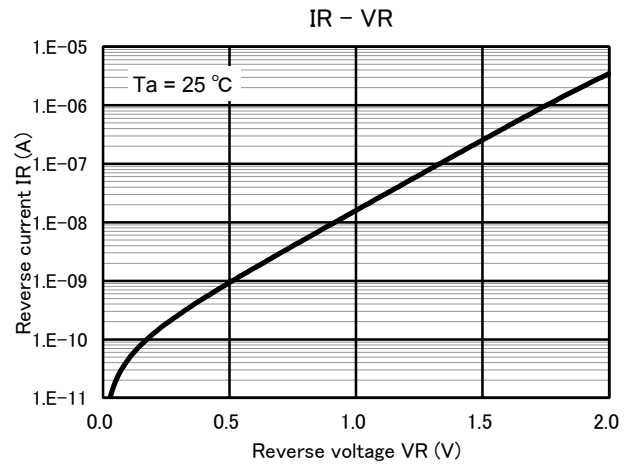
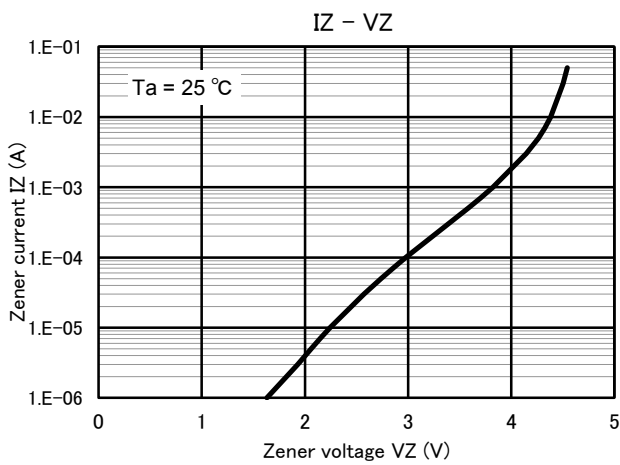
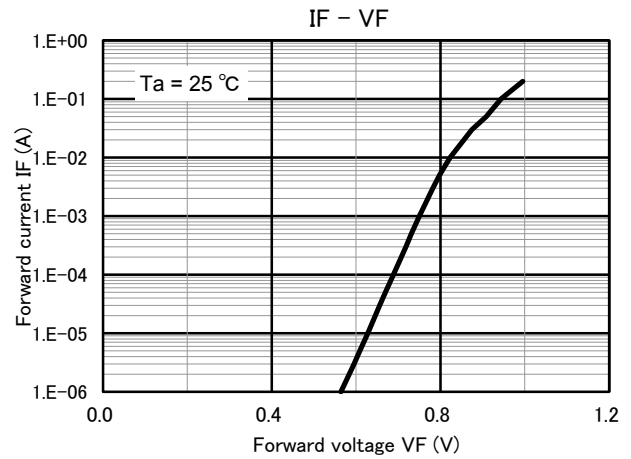
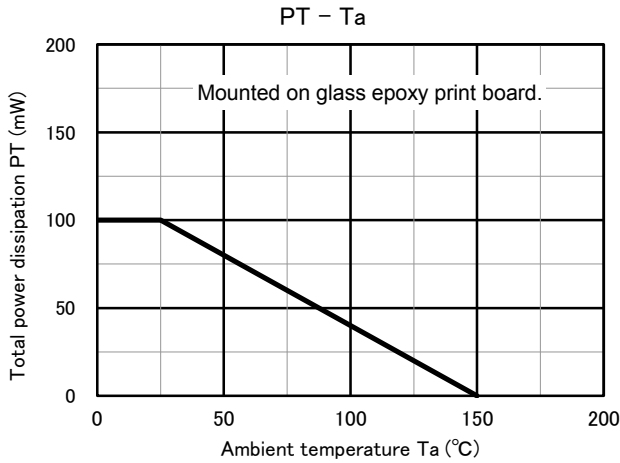
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 5 mA	4.09		4.52	V
Zener operating resistance	RZ	IZ = 5 mA			130	Ω
Reverse current	IR	VR = 1.0 V			10	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		-0.9		mV/°C

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.  
2. Absolute frequency of input and output is 5 MHz.  
3. \*1 The temperature must be controlled 25 °C for VZ mesurement.  
VZ value measured at other temperature must be adjusted to VZ ( 25 °C )  
\*2 VZ guaranteed 20 ms after current flow.  
\*3 Tj = 25 °C to 150 °C

Rank classification

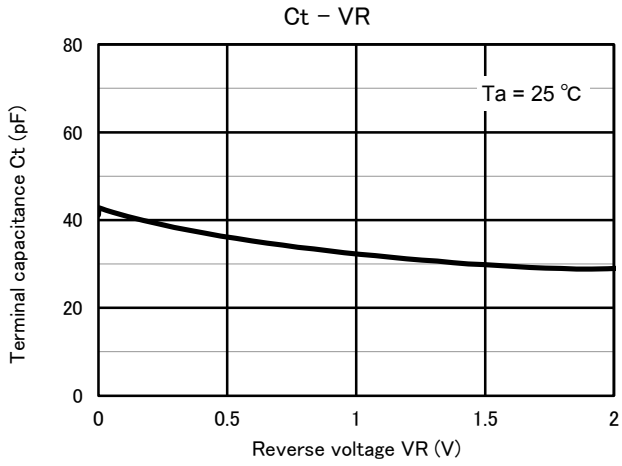
Code	M	0
Rank	M	No-rank
VZ	4.18 to 4.40	4.09 to 4.52
Marking symbol	9U	9J

Technical Data ( reference )



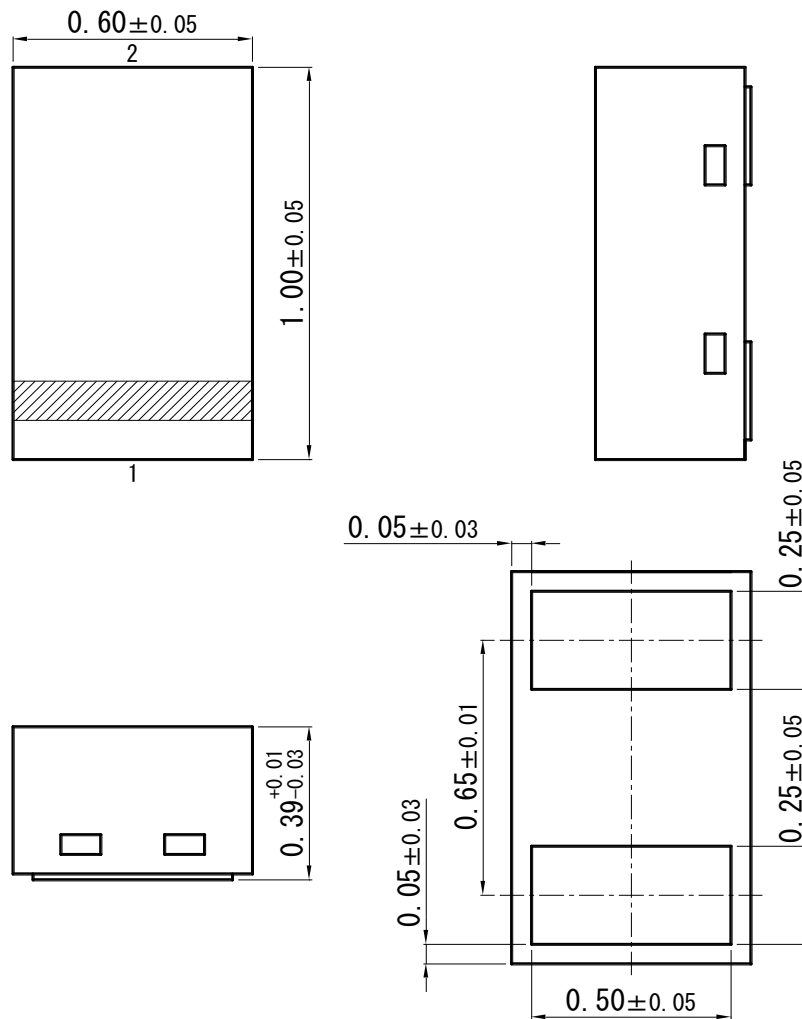


Technical Data ( reference )

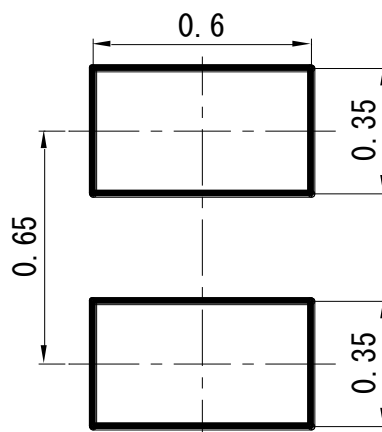


ML2-N3-B

Unit : mm



■ Land Pattern (Reference) (Unit : mm)



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